

## LP3878-ADJ Micropower 800mA Low Noise "Ceramic Stable" Adjustable Voltage Regulator for 1V to 5V Applications

Check for Samples: [LP3878-ADJ](#)

### FEATURES

- 1.0V to 5.5V Output
- Designed for Use with Low ESR Ceramic Capacitors
- Very Low Output Noise
- 8 Lead SO PowerPAD and WSON Surface Mount Package
- <10  $\mu$ A Quiescent Current in Shutdown
- Low Ground Pin Current at all Loads
- Over-Temperature/Over-Current Protection
- -40°C to +125°C Operating Junction Temperature Range

### APPLICATIONS

- ASIC Power Supplies In:
  - Desktops, Notebooks and Graphic Cards
  - Set Top Boxes, Printers and Copiers
- DSP and FPGA Power Supplies
- SMPS Post-Regulator
- Medical Instrumentation

### DESCRIPTION

The LP3878-ADJ is an 800 mA adjustable output voltage regulator designed to provide high performance and low noise in applications requiring output voltages as low as 1.0V.

Using an optimized VIP™ (Vertically Integrated PNP) process, the LP3878-ADJ delivers superior performance:

**Ground Pin Current:** Typically 5.5 mA @ 800 mA load, and 180  $\mu$ A @ 100  $\mu$ A load.

**Low Power Shutdown:** The LP3878-ADJ draws less than 10  $\mu$ A quiescent current when shutdown pin is pulled low.

**Precision Output:** Ensured output voltage accuracy is 1% at room temperature.

**Low Noise:** Broadband output noise is only 18  $\mu$ V (typical) with 10 nF bypass capacitor.

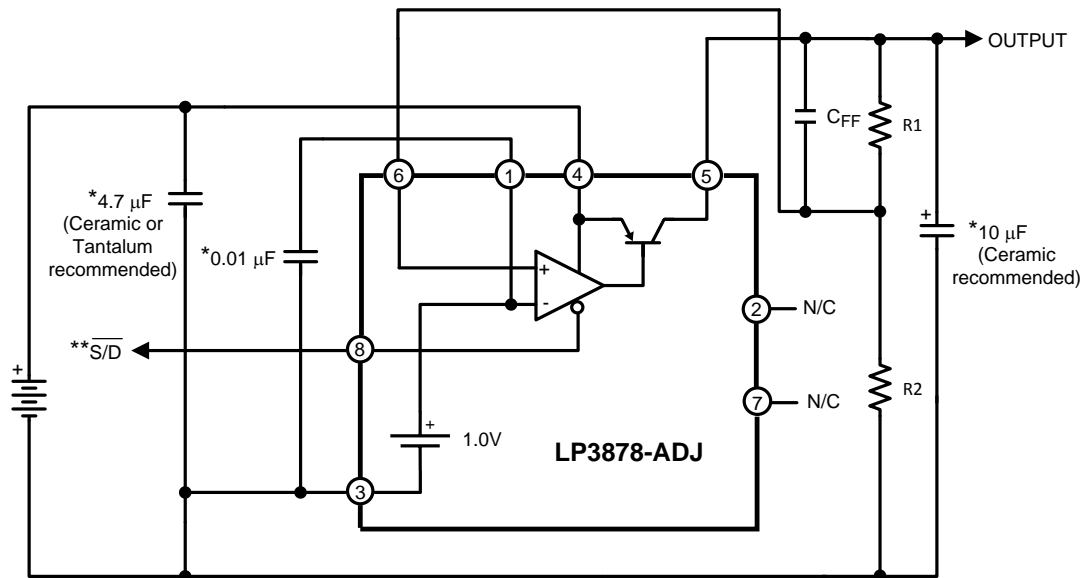


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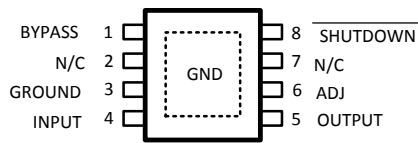
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**Basic Application Circuit**

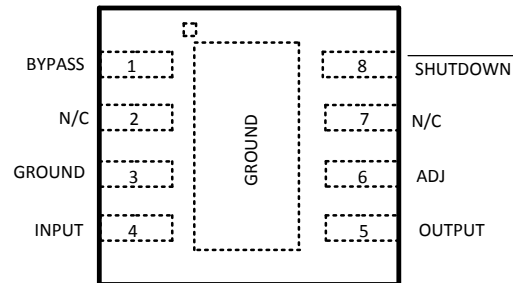


\*Capacitance values shown are minimum required to assure stability. Larger output capacitor provides improved dynamic response. Output capacitor must meet ESR requirements (see Application Information).  
 \*\*The Shutdown pin must be actively terminated (see [Application Information](#)). Tie to INPUT (Pin 4) if not used.

**Connection Diagram**



**Figure 1. 8 Lead SO PowerPAD Package (DDA) - Top View**  
 See Package Number DDA0008A



**Figure 2. 8 Lead WSON Surface Mount Package (NGT) Top View**  
 See Package Number NGT0008A

**PIN DESCRIPTIONS**

Pin	Name	Function
1	BYPASS	The capacitor connected between BYPASS and GROUND lowers output noise voltage level and is required for loop stability.
2	N/C	DO NOT CONNECT. This pin is used for post package test and must be left floating.
3	GROUND	Device ground.
4	INPUT	Input source voltage.
5	OUTPUT	Regulated output voltage.
6	ADJ	Provides feedback to error amplifier from the resistive divider that sets the output voltage.
7	N/C	No internal connection.
8	SHUTDOWN	Output is enabled above turn-on threshold voltage. Pull down to turn off regulator output.
SO PowerPAD, WSON DAP	SUBSTRATE GROUND	The exposed die attach pad should be connected to a thermal pad at ground potential. For additional information on using TI's Non Pull Back WSON package, please refer to WSON application note <a href="#">AN-1187</a>



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

**Absolute Maximum Ratings<sup>(1)(2)</sup>**

Storage Temperature Range	-65°C to +150°C
Operating Junction Temperature Range	-40°C to +125°C
Lead Temperature (Soldering, 5 seconds)	260°C
ESD Rating <sup>(3)</sup>	2 kV
Shutdown Pin	1kV
Power Dissipation <sup>(4)</sup>	Internally Limited
Input Supply Voltage (Survival)	-0.3V to +16V
Input Supply Voltage (Typical Operating)	2.5V to +16V
ADJ Pin	-0.3V to +6V
Output Voltage (Survival) <sup>(5)</sup>	-0.3V to +6V
I <sub>OUT</sub> (Survival)	Short Circuit Protected
Input-Output Voltage (Survival) <sup>(6)</sup>	-0.3V to +16V

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the component may occur. Electrical specifications do not apply when operating the device outside of its rated operating conditions.
- (2) If Military/Aerospace specified devices are required, please contact the TI Sales Office/ Distributors for availability and specifications.
- (3) ESD testing was performed using Human Body Model, a 100 pF capacitor discharged through a 1.5 kΩ resistor.
- (4) The maximum allowable power dissipation is a function of the maximum junction temperature, T<sub>J</sub>(MAX), the junction-to-ambient thermal resistance, θ<sub>J-A</sub>, and the ambient temperature, T<sub>A</sub>. The maximum allowable power dissipation at any ambient temperature is calculated using:

$$P(MAX) = \frac{T_J(MAX) - T_A}{\theta_{J-A}}$$

The value of θ<sub>J-A</sub> for the WSON (NGT) and SO PowerPAD (DDA) packages are specifically dependent on PCB trace area, trace material, and the number of layers and thermal vias. If a four layer board is used with maximum vias from the IC center to the heat dissipating copper layers, values of θ<sub>J-A</sub> which can be obtained are approximately 60°C/W for the SO PowerPAD-8 and 40°C/W for the WSON-8 package. For improved thermal resistance and power dissipation for the WSON package, refer to Application Note [AN-1187](#). Exceeding the maximum allowable power dissipation will cause excessive die temperature, and the regulator will go into thermal shutdown.

- (5) If used in a dual-supply system where the regulator load is returned to a negative supply, the LP3878-ADJ output must be diode-clamped to ground.
- (6) The output PNP structure contains a diode between the V<sub>IN</sub> and V<sub>OUT</sub> terminals that is normally reverse-biased. Forcing the output above the input will turn on this diode and may induce a latch-up mode which can damage the part (see Application Hints).

## Electrical Characteristics

Limits in standard typeface are for  $T_J = 25^\circ\text{C}$ , and limits in **boldface type** apply over the temperature range of  $-40^\circ\text{C}$  to  $125^\circ\text{C}$ . Limits are specified through design, testing, or correlation. The limits are used to calculate TI's Average Outgoing Quality Level (AOQL). Unless otherwise specified:  $V_{IN} = 3.0\text{V}$ ,  $V_{OUT} = 1\text{V}$ ,  $I_L = 1\text{ mA}$ ,  $C_{OUT} = 10\text{ }\mu\text{F}$ ,  $C_{IN} = 4.7\text{ }\mu\text{F}$ ,  $V_{S/D} = 2\text{V}$ ,  $C_{BYPASS} = 10\text{ nF}$ .

Symbol	Parameter	Conditions	Min	Typical	Max	Units
$V_{ADJ}$	Adjust Pin Voltage		0.99	1.00	1.01	V
		$1\text{ mA} \leq I_L \leq 800\text{ mA}$ $3.0\text{V} \leq V_{IN} \leq 6\text{V}$	0.98 <b>0.97</b>	1.00	1.02 <b>1.03</b>	
$\frac{\Delta V_{OUT}}{\Delta V_{IN}}$	Output Voltage Line Regulation	$3.0\text{V} \leq V_{IN} \leq 16\text{V}$		0.007	0.014 <b>0.032</b>	%/V
$V_{IN}(\text{min})$	Minimum Input Voltage Required To Maintain Output Regulation	$I_L = 800\text{ mA}$ , $V_{OUT} \geq V_{OUT(\text{NOM})} - 1\%$		2.5	<b>3.1</b>	V
		$I_L = 800\text{ mA}$ $V_{OUT} \geq V_{OUT(\text{NOM})} - 1\%$ $0 \leq T_J \leq 125^\circ\text{C}$		2.5	<b>2.8</b>	
		$I_L = 750\text{ mA}$ , $V_{OUT} \geq V_{OUT(\text{NOM})} - 1\%$		2.5	<b>3.0</b>	
$V_{DO}$	Dropout Voltage <sup>(1)</sup> $V_{OUT} = 3.8\text{V}$	$I_L = 100\text{ }\mu\text{A}$		1	2 <b>3</b>	mV
		$I_L = 200\text{ mA}$		150	200 <b>300</b>	
		$I_L = 800\text{ mA}$		475	600 <b>1100</b>	
$I_{GND}$	Ground Pin Current	$I_L = 100\text{ }\mu\text{A}$		180	200 <b>225</b>	$\mu\text{A}$
		$I_L = 200\text{ mA}$		1.5	2 <b>3.5</b>	mA
		$I_L = 800\text{ mA}$		5.5	8.5 <b>15</b>	
$I_O(\text{PK})$	Peak Output Current	$V_{OUT} \geq V_{OUT(\text{NOM})} - 5\%$		1200		mA
$I_O(\text{MAX})$	Short Circuit Current	$R_L = 0$ (Steady State)		1300		
$e_n$	Output Noise Voltage (RMS)	$\text{BW} = 100\text{ Hz to }100\text{ kHz}$ $C_{BYPASS} = 10\text{ nF}$		18		$\mu\text{V}(\text{RMS})$
$\frac{\Delta V_{OUT}}{\Delta V_{IN}}$	Ripple Rejection	$f = 1\text{ kHz}$		60		dB
$I_{ADJ}$	ADJ Pin Bias Current (Sourcing)	$I_L = 800\text{ mA}$		200		nA
<b>SHUTDOWN INPUT</b>						
$V_{S/D}$	S/D Input Voltage	$V_H = \text{Output ON}$		1.4	<b>1.6</b>	V
		$V_L = \text{Output OFF}$ , $I_{IN} \leq 10\text{ }\mu\text{A}$	<b>0.04</b>	0.20		
		$V_{OUT} \leq 10\text{ mV}$ , $I_{IN} \leq 50\text{ }\mu\text{A}$		0.6		
$I_{S/D}$	S/D Input Current	$V_{S/D} = 0$		0.02	<b>-1</b>	$\mu\text{A}$
		$V_{S/D} = 5\text{V}$		5	<b>15</b>	

(1) Dropout voltage spec applies only if  $V_{IN}$  is sufficient so that it does not limit regulator operation.

### Typical Performance Characteristics

Unless otherwise specified:  $V_{IN} = 3.3V$ ,  $V_{OUT} = 1V$ ,  $I_L = 1\text{ mA}$ ,  $C_{IN} = 4.7\text{ }\mu\text{F}$ ,  $C_{OUT} = 10\text{ }\mu\text{F}$ ,  $V_{SD} = 2V$ ,  $C_{BYP} = 10\text{ nF}$ ,  $T_J = 25^\circ\text{C}$ .

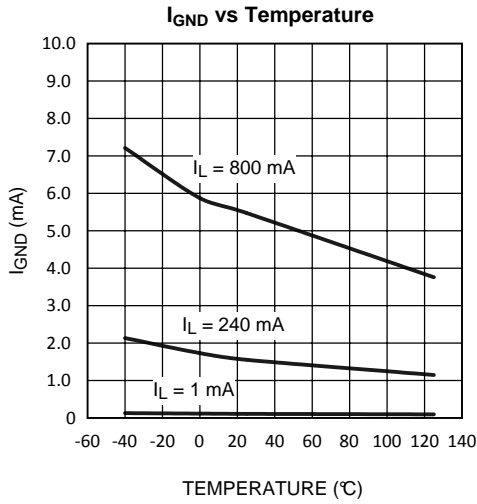


Figure 3.

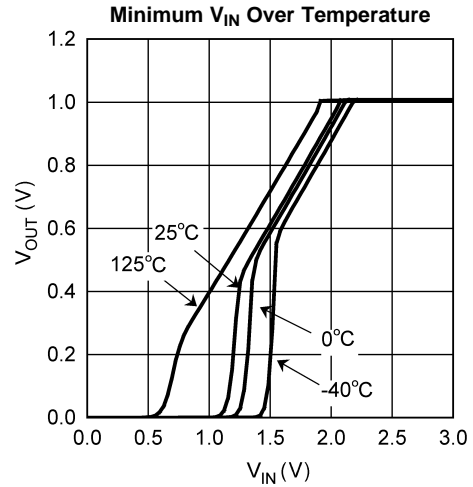


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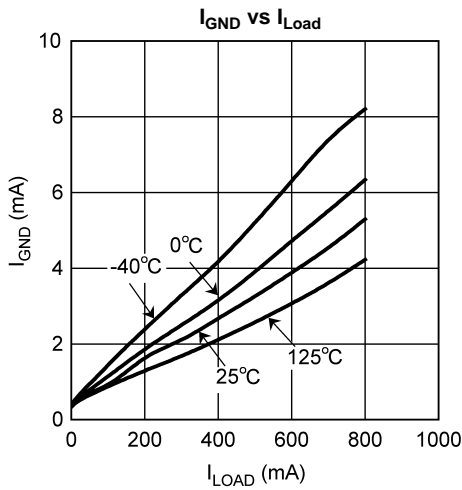


Figure 5.

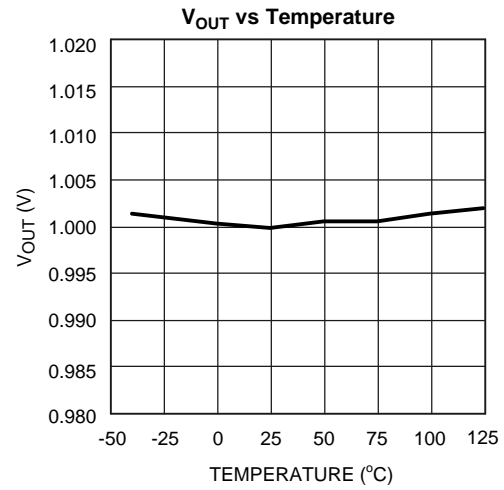


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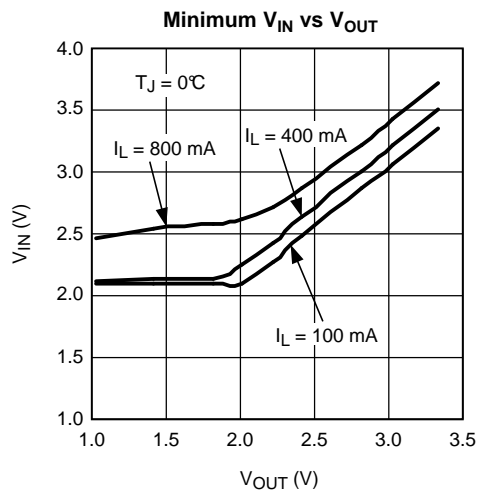


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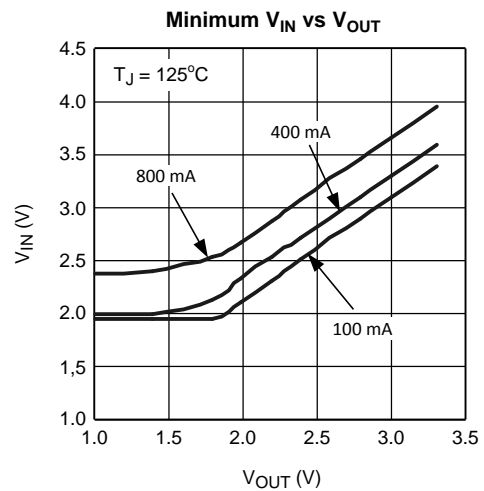


Figure 8.

**Typical Performance Characteristics (continued)**

Unless otherwise specified:  $V_{IN} = 3.3V$ ,  $V_{OUT} = 1V$ ,  $I_L = 1\text{ mA}$ ,  $C_{IN} = 4.7\text{ }\mu\text{F}$ ,  $C_{OUT} = 10\text{ }\mu\text{F}$ ,  $V_{SD} = 2V$ ,  $C_{BYP} = 10\text{ nF}$ ,  $T_J = 25^\circ\text{C}$ .

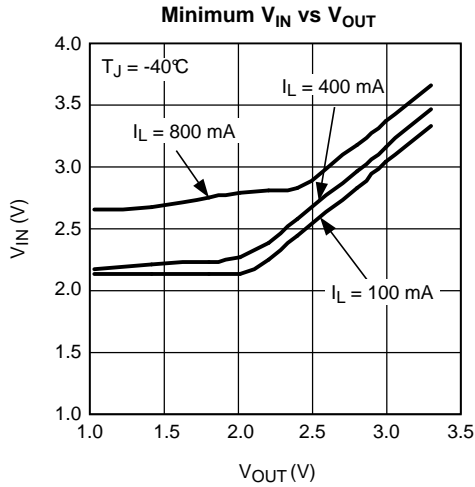


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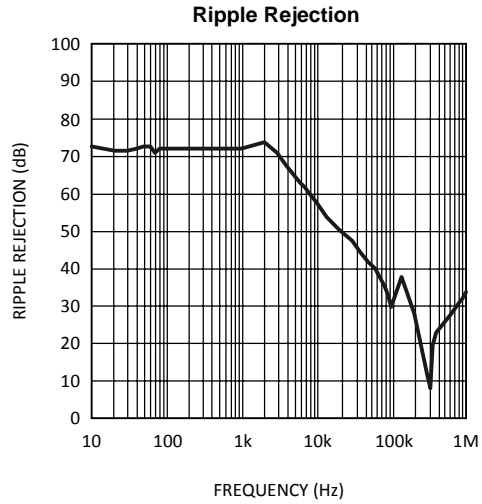


Figure 10.

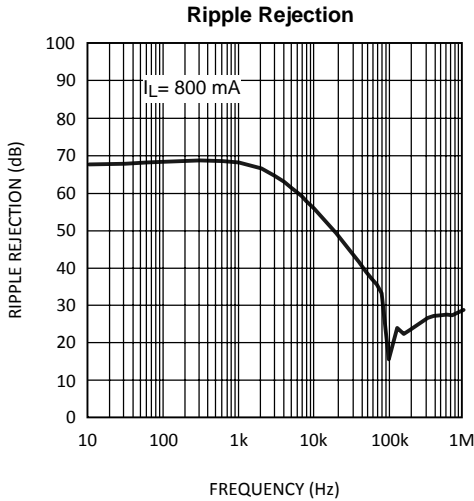


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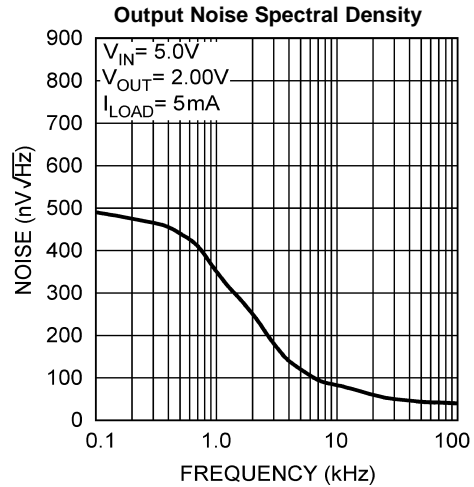


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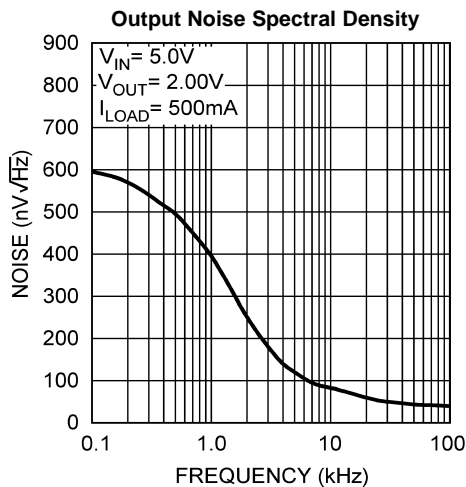


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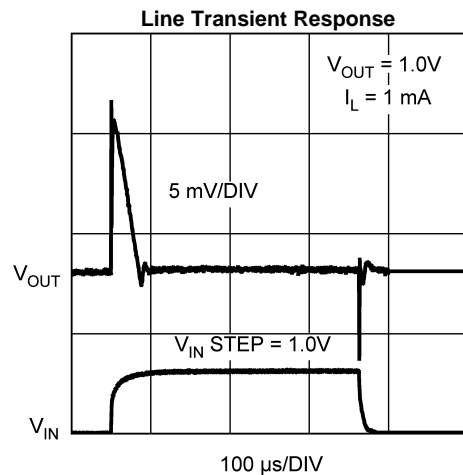
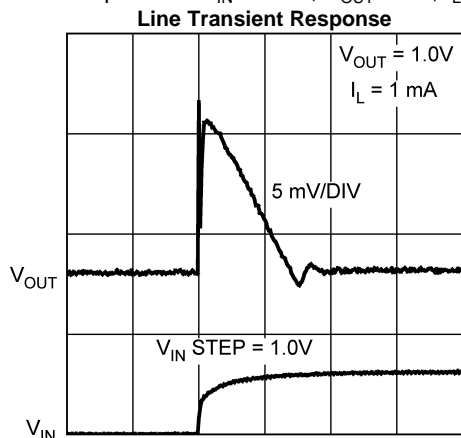


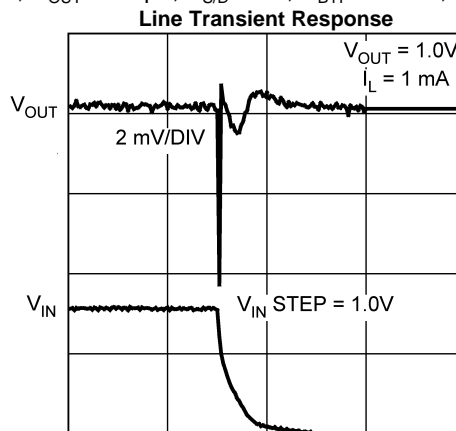
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Typical Performance Characteristics (continued)

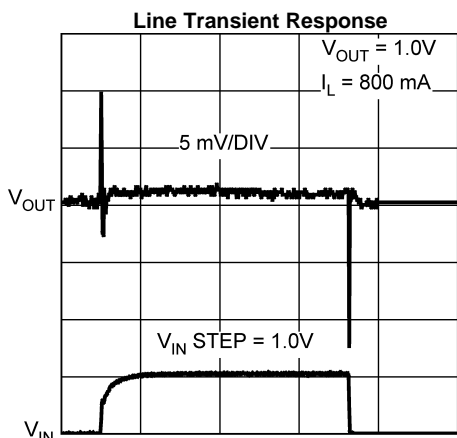
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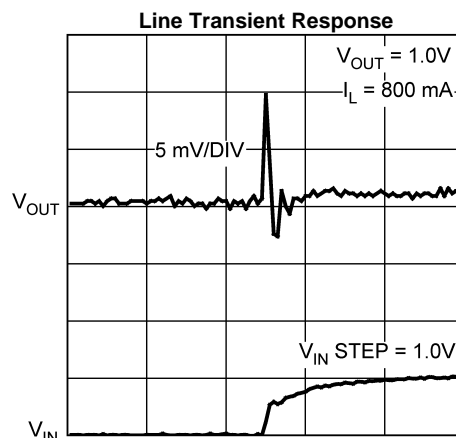
25  $\mu\text{s}/\text{DIV}$   
Figure 15.



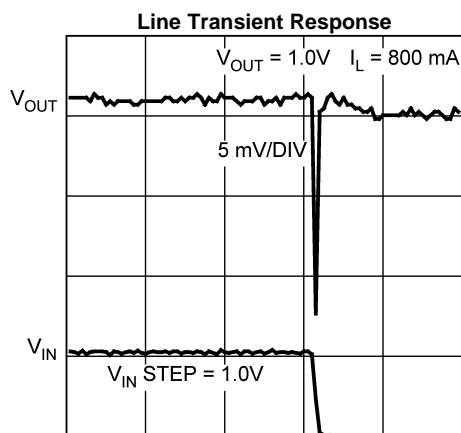
25  $\mu\text{s}/\text{DIV}$   
Figure 16.



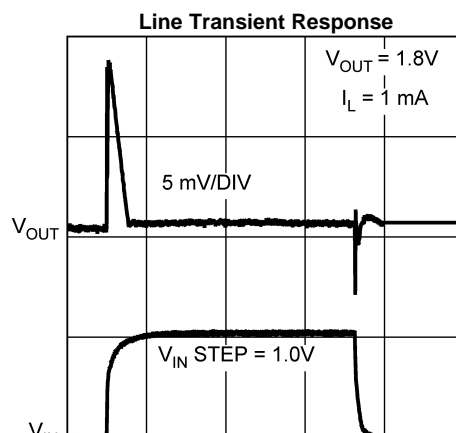
100  $\mu\text{s}/\text{DIV}$   
Figure 17.



20  $\mu\text{s}/\text{DIV}$   
Figure 18.



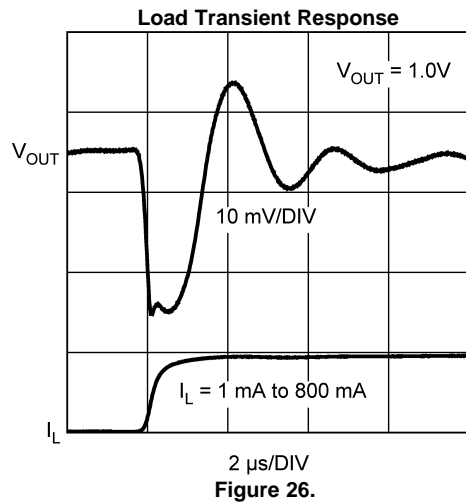
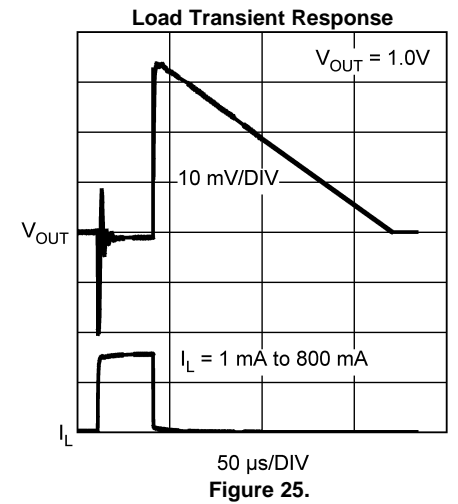
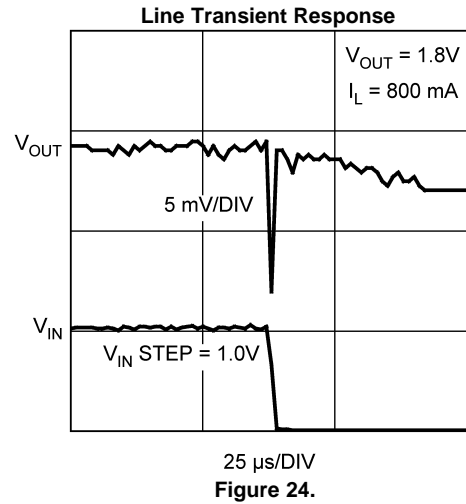
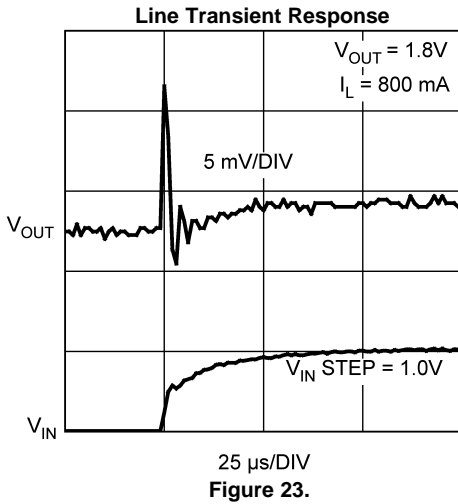
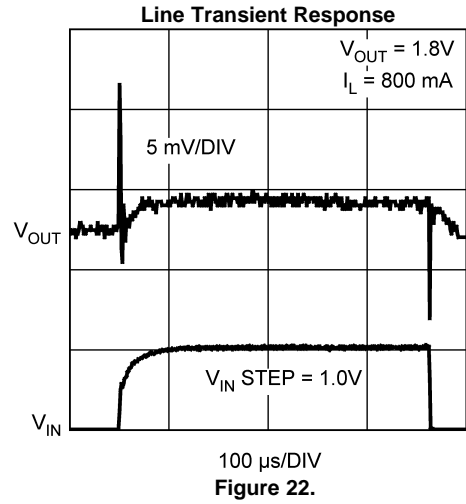
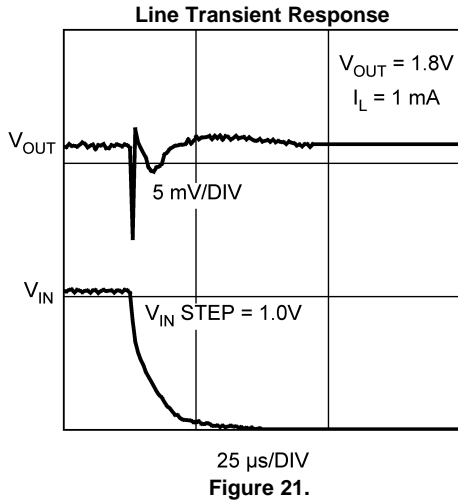
20  $\mu\text{s}/\text{DIV}$   
Figure 19.



100  $\mu\text{s}/\text{DIV}$   
Figure 20.

**Typical Performance Characteristics (continued)**

Unless otherwise specified:  $V_{IN} = 3.3V$ ,  $V_{OUT} = 1V$ ,  $I_L = 1\text{ mA}$ ,  $C_{IN} = 4.7\text{ }\mu\text{F}$ ,  $C_{OUT} = 10\text{ }\mu\text{F}$ ,  $V_{SD} = 2V$ ,  $C_{BYP} = 10\text{ nF}$ ,  $T_J = 25^\circ\text{C}$ .





**Typical Performance Characteristics (continued)**

Unless otherwise specified:  $V_{IN} = 3.3V$ ,  $V_{OUT} = 1V$ ,  $I_L = 1\text{ mA}$ ,  $C_{IN} = 4.7\ \mu F$ ,  $C_{OUT} = 10\ \mu F$ ,  $V_{S/D} = 2V$ ,  $C_{BYP} = 10\text{ nF}$ ,  $T_J = 25^\circ C$ .

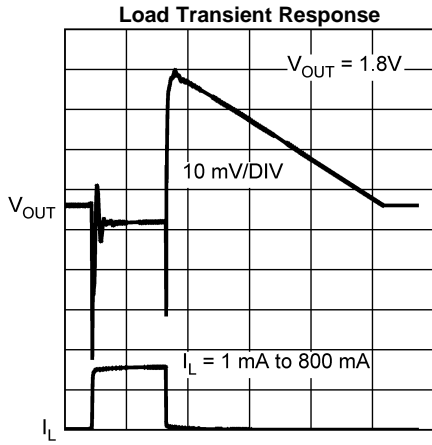


Figure 27.

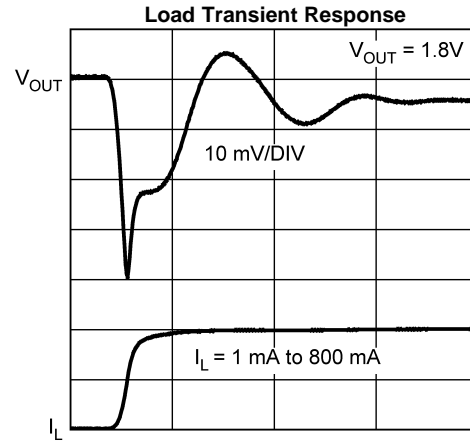


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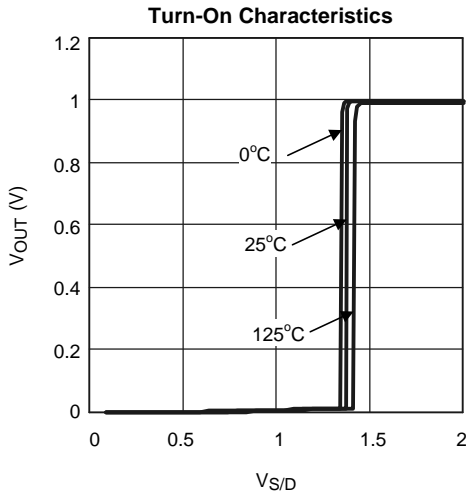


Figure 29.

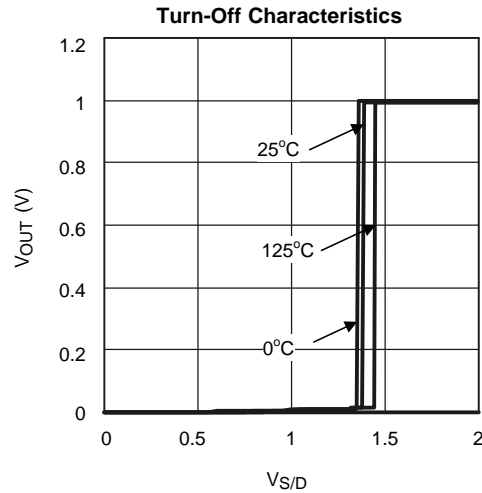
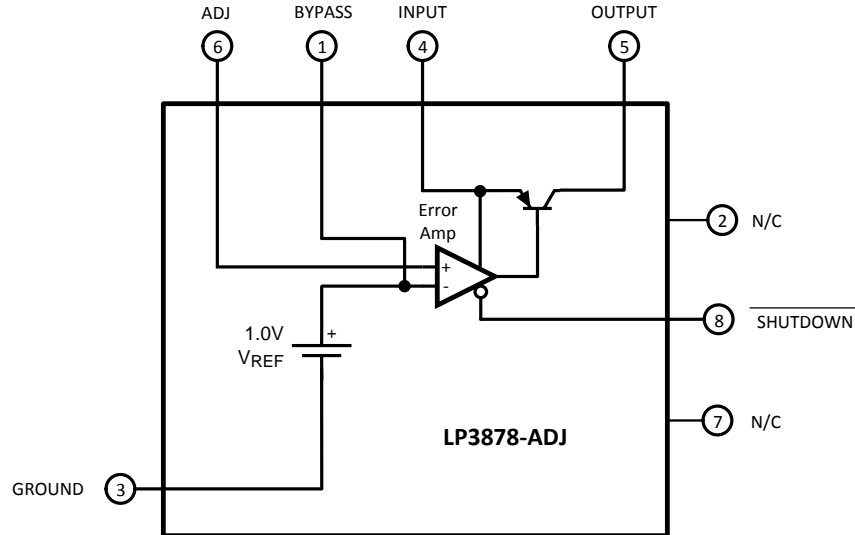


Figure 30.

### Block Diagram



### APPLICATION INFORMATION

#### PACKAGE INFORMATION

The LP3878-ADJ is offered in the 8 lead SO PowerPAD or WSON surface mount packages to allow for increased power dissipation compared to the SO-8 and Mini SO-8. For details on thermal performance as well as mounting and soldering specifications, refer to Application Note [AN-1187](#).

#### EXTERNAL CAPACITORS

Like any low-dropout regulator, the LP3878-ADJ requires external capacitors for regulator stability. These capacitors must be correctly selected for good performance.

#### INPUT CAPACITOR:

A capacitor whose value is at least 4.7  $\mu\text{F}$  ( $\pm 20\%$ ) is required between the LP3878-ADJ input and ground. A good quality X5R / X7R ceramic capacitor should be used.

Capacitor tolerance and temperature variation must be considered when selecting a capacitor (see [CAPACITOR CHARACTERISTICS](#) section) to assure the minimum requirement of input capacitance is met over all operating conditions.

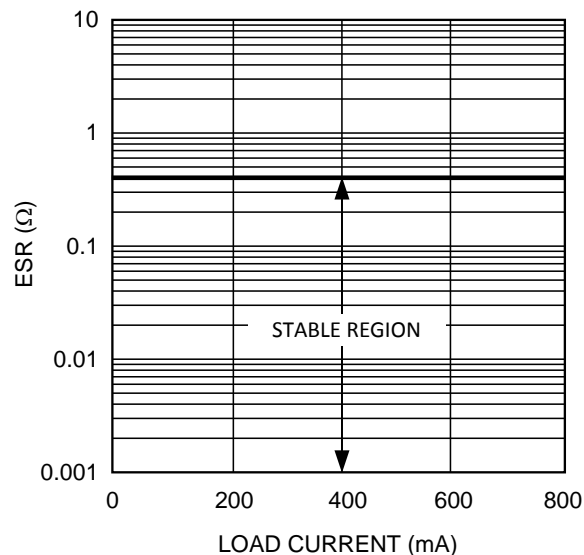
The input capacitor must be located not more than 0.5" from the input pin and returned to a clean analog ground. Any good quality ceramic or tantalum capacitor may be used, assuming the minimum input capacitance requirement is met.

#### OUTPUT CAPACITOR:

The LP3878-ADJ requires a ceramic output capacitor whose size is at least 10  $\mu\text{F}$  ( $\pm 20\%$ ). A good quality X5R / X7R ceramic capacitor should be used. Capacitance tolerance and temperature characteristics must be considered when selecting an output capacitor.

The LP3878-ADJ is designed specifically to work with ceramic output capacitors, utilizing circuitry which allows the regulator to be stable across the entire range of output current with an ultra low ESR output capacitor.

The output capacitor selected must meet the requirement for minimum amount of capacitance and also have an ESR (equivalent series resistance) value which is within the stable range. A curve is provided which shows the stable ESR range as a function of load current (see [Figure 31](#)).



**Figure 31. Stable Region For Output Capacitor ESR**

**NOTE**

**Important:** The output capacitor must maintain its ESR within the stable region over the full operating temperature range of the application to assure stability.

The output capacitor ESR forms a zero which is required to add phase lead near the loop gain crossover frequency, typically in the range of 50kHz to 200 kHz. The ESR at lower frequencies is of no importance. Some capacitor manufacturers list ESR at low frequencies only, and some give a formula for Dissipation Factor which can be used to calculate a value for a term referred to as ESR. However, since the DF formula is usually at a much lower frequency than the range listed above, it will give an unrealistically high value. If good quality X5R or X7R ceramic capacitors are used, the actual ESR in the 50 kHz to 200 kHz range will not exceed 25 milli Ohms. If these are used as output capacitors for the LP3878-ADJ, the regulator stability requirements are satisfied.

It is important to remember that capacitor tolerance and variation with temperature must be taken into consideration when selecting an output capacitor so that the minimum required amount of output capacitance is provided over the full operating temperature range. (See [CAPACITOR CHARACTERISTICS](#)).

The output capacitor must be located not more than 0.5" from the output pin and returned to a clean analog ground.

**NOISE BYPASS CAPACITOR:**

The 10 nF capacitor on the Bypass pin significantly reduces noise on the regulator output and is required for loop stability. However, the capacitor is connected directly to a high-impedance circuit in the bandgap reference.

Because this circuit has only a few microamperes flowing in it, any significant loading on this node will cause a change in the regulated output voltage. For this reason, DC leakage current through the noise bypass capacitor must never exceed 100 nA, and should be kept as low as possible for best output voltage accuracy.

The types of capacitors best suited for the noise bypass capacitor are ceramic and film. High-quality ceramic capacitors with either NPO or COG dielectric typically have very low leakage. 10 nF polypropylene and polycarbonate film capacitors are available in small surface-mount packages and typically have extremely low leakage current.

## FEEDFORWARD CAPACITOR

The feedforward capacitor designated  $C_{FF}$  in the Basic Application circuit is required to increase phase margin and assure loop stability. Improved phase margin also gives better transient response to changes in load or input voltage, and faster settling time on the output voltage when transients occur.  $C_{FF}$  forms both a pole and zero in the loop gain, the zero providing beneficial phase lead (which increases phase margin) and the pole adding undesirable phase lag (which should be minimized). The zero frequency is determined both by the value of  $C_{FF}$  and  $R1$ :

$$f_z = 1 / (2 \times \pi \times C_{FF} \times R1) \quad (1)$$

The pole frequency resulting from  $C_{FF}$  is determined by the value of  $C_{FF}$  and the parallel combination of  $R1$  and  $R2$ :

$$f_p = 1 / (2 \times \pi \times C_{FF} \times (R1 // R2)) \quad (2)$$

At higher output voltages where  $R1$  is much greater than  $R2$ , the value of  $R2$  primarily determines the value of the parallel combination of  $R1 // R2$ . This puts the pole at a much higher frequency than the zero. As the regulated output voltage is reduced (and the value of  $R1$  decreases), the parallel effect of  $R2$  diminishes and the two equations become equal (at which point the pole and zero cancel out). Because the pole frequency gets closer to the zero at lower output voltages, the beneficial effects of  $C_{FF}$  are increased if the frequency range of the zero is shifted slightly higher for applications with low  $V_{out}$  (because then the pole adds less phase lag at the loop's crossover frequency).

$C_{FF}$  should be selected to place the pole zero pair at a frequency where the net phase lead added to the loop at the crossover frequency is maximized. The following design guidelines were obtained from bench testing to optimize phase margin, transient response, and settling time:

**For  $V_{out} \leq 2.5V$ :**  $C_{FF}$  should be selected to set the zero frequency in the range of about 50 kHz to 200 kHz.

**For  $V_{out} > 2.5V$ :**  $C_{FF}$  should be selected to set the zero frequency in the range of about 20 kHz to 100 kHz.

## CAPACITOR CHARACTERISTICS

### CERAMIC:

The LP3878-ADJ was designed to work with ceramic capacitors on the output to take advantage of the benefits they offer: for capacitance values in the 10  $\mu F$  range, ceramics are the least expensive and also have the lowest ESR values (which makes them best for eliminating high-frequency noise). The ESR of a typical 10  $\mu F$  ceramic capacitor is in the range of 5 m $\Omega$  to 10 m $\Omega$ , which meets the ESR limits required for stability by the LP3878-ADJ.

One disadvantage of ceramic capacitors is that their capacitance can vary with temperature. Many large value ceramic capacitors ( $\geq 2.2 \mu F$ ) are manufactured with the Z5U or Y5V temperature characteristic, which results in the capacitance dropping by more than 50% as the temperature goes from 25°C to 85°C.

Another significant problem with Z5U and Y5V dielectric devices is that the capacitance drops severely with applied voltage. A typical Z5U or Y5V capacitor can lose 60% of its rated capacitance with half of the rated voltage applied to it.

**For these reasons, X7R and X5R type ceramic capacitors must be used on the input and output of the LP3878-ADJ.**

## SHUTDOWN INPUT OPERATION

The LP3878-ADJ is shut off by pulling the Shutdown input low, and turned on by pulling it high. If this feature is not to be used, the Shutdown input should be tied to  $V_{IN}$  to keep the regulator output on at all times.

To assure proper operation, the signal source used to drive the Shutdown input must be able to swing above and below the specified turn-on/turn-off voltage thresholds listed in the [Electrical Characteristics](#) section under  $V_{ON/OFF}$ .

## REVERSE INPUT-OUTPUT VOLTAGE

The PNP power transistor used as the pass element in the LP3878-ADJ has an inherent diode connected between the regulator output and input.

During normal operation (where the input voltage is higher than the output) this diode is reverse-biased.

However, if the output is pulled above the input, this diode will turn ON and current will flow into the regulator output.

In such cases, a parasitic SCR can latch which will allow a high current to flow into  $V_{IN}$  (and out the ground pin), which can damage the part.

In any application where the output may be pulled above the input, an external Schottky diode must be connected from  $V_{IN}$  to  $V_{OUT}$  (cathode on  $V_{IN}$ , anode on  $V_{OUT}$ ), to limit the reverse voltage across the LP3878-ADJ to 0.3V (see Absolute Maximum Ratings).

## SETTING THE OUTPUT VOLTAGE

The output voltage is set using resistors R1 and R2 (see [Basic Application Circuit](#)).

The formula for output voltage is:

$$V_{OUT} = V_{ADJ} \times (1 + (R_1 / R_2)) \quad (3)$$

R2 must be less than 5 k $\Omega$  to ensure loop stability.

To prevent voltage errors, R1 and R2 must be located near the LP3878-ADJ and connected via traces with no other currents flowing in them (Kelvin connect). The bottom of the R1/R2 divider must be connected directly to the LP3878-ADJ ground pin.

## REVISION HISTORY

Changes from Revision A (April 2013) to Revision B	Page
• Changed layout of National Data Sheet to TI format .....	<a href="#">13</a>

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
LP3878MR-ADJ	ACTIVE	SO PowerPAD	DDA	8	95	TBD	Call TI	Call TI		3878 MRADJ	<a href="#">Samples</a>
LP3878MR-ADJ/NOPB	ACTIVE	SO PowerPAD	DDA	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR		3878 MRADJ	<a href="#">Samples</a>
LP3878MRX-ADJ	ACTIVE	SO PowerPAD	DDA	8	2500	TBD	Call TI	Call TI		3878 MRADJ	<a href="#">Samples</a>
LP3878MRX-ADJ/NOPB	ACTIVE	SO PowerPAD	DDA	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR		3878 MRADJ	<a href="#">Samples</a>
LP3878SD-ADJ/NOPB	ACTIVE	WSON	NGT	8	1000	Green (RoHS & no Sb/Br)	SN	Level-1-260C-UNLIM		3878ADJ	<a href="#">Samples</a>
LP3878SDX-ADJ/NOPB	ACTIVE	WSON	NGT	8	4500	Green (RoHS & no Sb/Br)	SN	Level-1-260C-UNLIM		3878ADJ	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

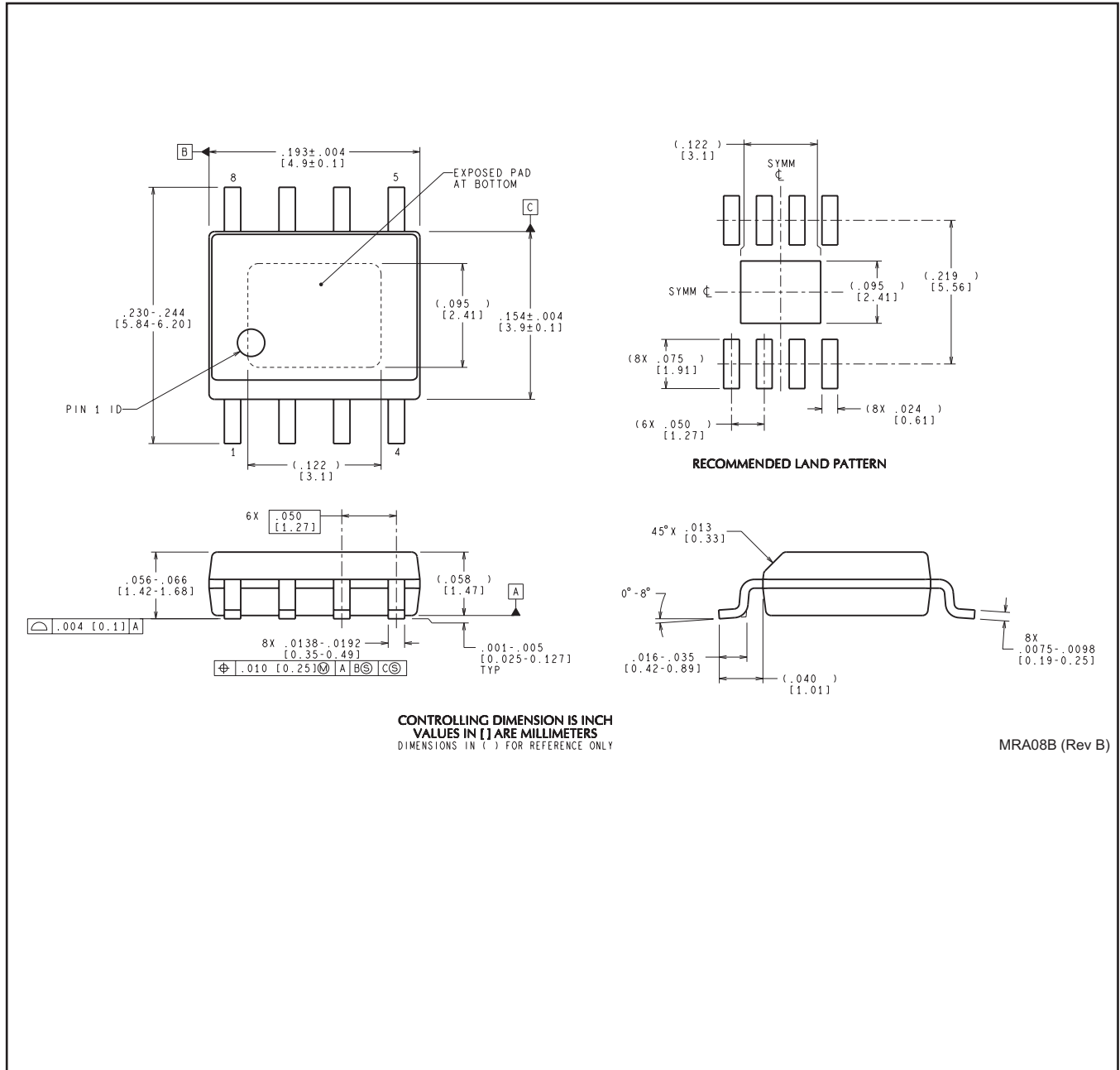
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LP3878MRX-ADJ	SO Power PAD	DDA	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LP3878MRX-ADJ/NOPB	SO Power PAD	DDA	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LP3878SD-ADJ/NOPB	WSO	NGT	8	1000	178.0	12.4	4.3	4.3	1.3	8.0	12.0	Q1
LP3878SDX-ADJ/NOPB	WSO	NGT	8	4500	330.0	12.4	4.3	4.3	1.3	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

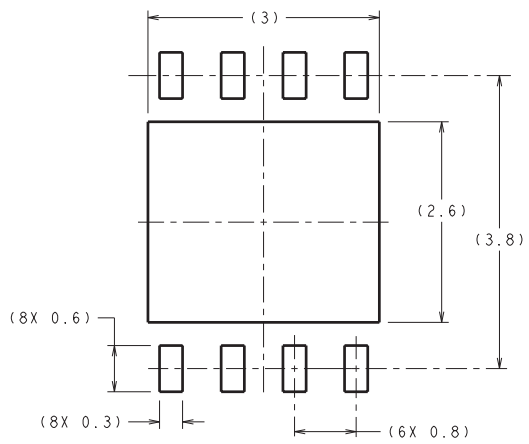
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LP3878MRX-ADJ	SO PowerPAD	DDA	8	2500	367.0	367.0	35.0
LP3878MRX-ADJ/NOPB	SO PowerPAD	DDA	8	2500	367.0	367.0	35.0
LP3878SD-ADJ/NOPB	WSON	NGT	8	1000	203.0	190.0	41.0
LP3878SDX-ADJ/NOPB	WSON	NGT	8	4500	367.0	367.0	35.0

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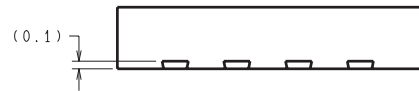


MRA08B (Rev B)

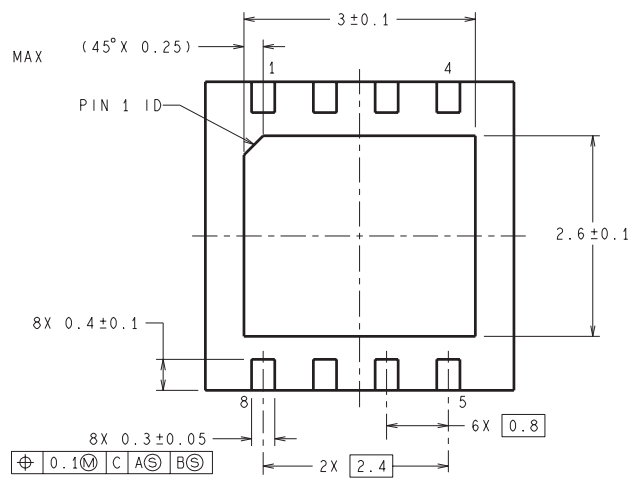
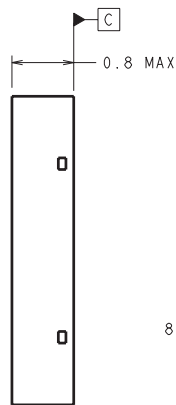
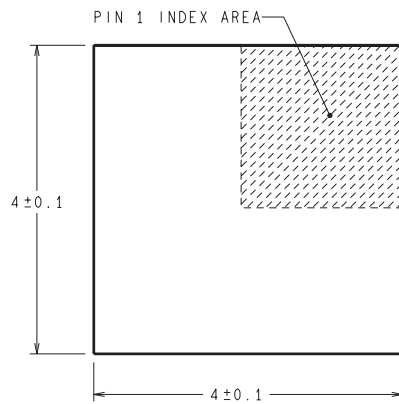
NGT0008A



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